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(54) Title: SOLDERING FLUX, SOLDER PASTE AND METHOD FOR MANUFACTURING SOLDERING FLUX

(57) Abstract: A soldering flux includes rosin, a thixotropic agent, an activator, an antioxidant and a solvent, in which rosin ester is included as the rosin, a content of the rosin ester is set in a range of 20 mass% to 50 mass% with respect to the entire flux, and one or two or more selected from polyamides, cured castor oil, derivatives thereof and hydrocarbon-based waxes are included as the thixotropic agent.



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